

## BEST AVAILABLE COPY

1 tile with array with MEM ("5371654"   "5432681"   "5510655"   "5544017"   "5574561"   6 "6052287").PN.	USPAT; US-PGPUB; IBM_TDB	4/14/03 12:46
2 6185107.URPN.	USPAT	4/14/03 12:44
1 tile with sub-array with MEM	USPAT	4/14/03 12:45
	USPAT; US-PGPUB; IBM_TDB	4/14/03 12:46
9 tile\$3 with (array sub-array sub\$2array or (sub adj array)) with MEM	USPAT; US-PGPUB; IBM_TDB	4/14/03 12:50
3 ("5761350"   "6014240"   "6097857").PN.	USPAT	4/14/03 12:49
21 tile\$3 with MEM	USPAT; US-PGPUB; IBM_TDB	4/14/03 12:50
218 (silicon with insulat\$4) same MEM same substrate	USPAT; US-PGPUB; IBM_TDB	4/14/03 14:47
240 ((silicon with insulat\$4) or SOI) same MEM same substrate	USPAT; US-PGPUB; IBM_TDB	4/14/03 14:48
91 SOI same MEM same substrate (((silicon with insulat\$4) or SOI) same MEM same substrate) and	USPAT; US-PGPUB; IBM_TDB	4/14/03 14:49
85 mirror	USPAT; US-PGPUB; IBM_TDB	4/14/03 14:50
48 (SOI same MEM same substrate) and mirror	USPAT; US-PGPUB; IBM_TDB	4/14/03 15:52
2 ("5629790"   "5742419").PN.	USPAT	4/14/03 14:51
2 (("5629790") or ("6445841")).PN.	USPAT; US-PGPUB; IBM_TDB	4/14/03 15:52
29 underbump with metallurgy	USPAT; US-PGPUB; IBM_TDB	4/15/03 18:51
1 (underbump with metallurgy) same MEM ("0557132"   "3244947"   "3259814"   "3274458"   "3316465"   "3489965"   "3916080"   "3959577"   "3993123"   "4168480"   "4257905"   "4449580"   "4511873"   "4563697"   "4565901"   "4897508"	USPAT; US-PGPUB; IBM_TDB	4/15/03 13:36
20 "5046161"   "5325265"   "5475280"   "5627396").PN. (etch\$3 with insulat\$5) same MEM same (SOI or (silicon near2	USPAT	4/15/03 11:46
35 insulator)) ((etch\$3 adj stop) with insulat\$5) same MEM same (SOI or (silicon	USPAT; US-PGPUB; IBM_TDB	4/15/03 13:41
5 near2 insulator))	USPAT; US-PGPUB; IBM_TDB	4/15/03 13:49
3 (("6455841") or ("6025767") or ("5629790")).PN.	USPAT; US-PGPUB; IBM_TDB	4/15/03 13:50
29 underbump with metallurgy	USPAT; US-PGPUB; IBM_TDB	4/15/03 18:51
3 ( underbump with metallurgy) and MEM	USPAT; US-PGPUB; IBM_TDB	4/15/03 18:53
214 (solder with bump) and MEM	USPAT; US-PGPUB; IBM_TDB	4/15/03 18:53
16 (solder with bump) and MEM and metallurgy	USPAT; US-PGPUB; IBM_TDB	4/15/03 20:48
2 (("6445841") or ("5629790")).PN.	USPAT; US-PGPUB; IBM_TDB	4/15/03 19:24
2521 etch\$4 with thermal\$4 with oxidat\$4	USPAT; US-PGPUB; IBM_TDB	4/15/03 20:49
75 (etch\$4 with thermal\$4 with oxidat\$4) and MEM	USPAT; US-PGPUB; IBM_TDB	4/15/03 20:49
2 (("6400550") or ("6367252")).PN.	USPAT; US-PGPUB; IBM_TDB	4/15/03 19:24